

**ABSTRACT OF THE DISCLOSURE**

A miniaturized small memory card includes a substrate, at least one upper memory chip, at least the lower memory chip, one upper glue layer, and one lower glue layer, the substrate is formed with an upper surface and a lower surface, the upper surface is formed with a plurality of connected points, the lower surface is formed with a frame to cause a cavity, which formed a plurality of connected points, formed between the frame and the substrate, the frame is formed with a plurality of golden fingers, the golden fingers are electrically connected to an electric device, the upper memory chip, which is mounted on the upper surface of the substrate, electrically connected to the plurality of connected points of the upper surface, the lower memory chip, which is mounted on the cavity of the lower surface of the substrate, electrically connected to a plurality of connected points of the lower surface, the upper glue layer encapsulated the upper surface of the substrate, so that at least one upper memory chip will be packaged, the lower glue layer encapsulated the lower surface of the substrate, so that at least one lower memory chip will be packaged.